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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of

: **Confirmation No. 6334**

Koji MISHIMA et al.

: Attorney Docket No. 2003\_1305

Serial No. 10/660,483

: Group Art Unit 1742

Filed September 12, 2003

: Examiner William T. Leader

METHOD AND APPARATUS FOR PLATING  
SUBSTRATE WITH COPPER

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**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

Sir:

In response to the Office Action of March 27, 2006, please amend the above-referenced  
U.S. patent application as follows: